TAPE-ON HEAT SINK

ABSTRACT OF THE DISCLOSURE

The invention is to a heat sink and heat spreader (20)for mounting on a surface of a semiconductor device package. A heat sink plate (24)has first (21a) and second surfaces (21b) wherein the first surface (21a) serves as a thermal dissipation surface. An adhesive (24)is applied to the second surface (21b) of said heat sink plate (21) for adhering the heat sink to the surface of a semiconductor device package.

Figure 4